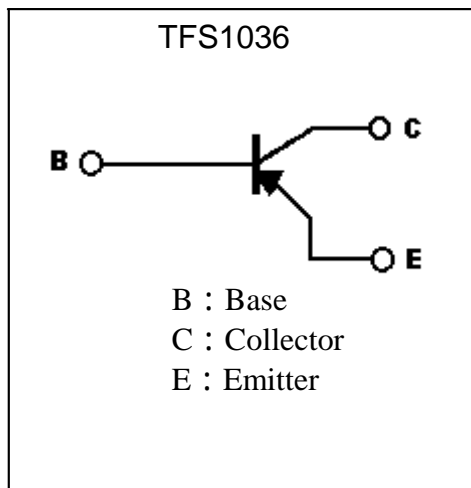


TFS1036

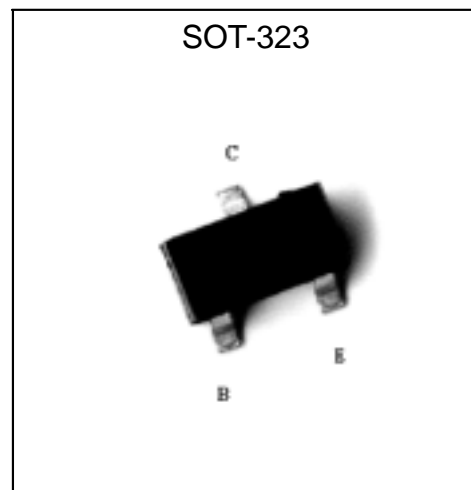
Description

- The TFS1036 is designed for general purpose amplifier applications. It is housed in the SOT-323/SC-70 package which is designed for low power surface mount applications.
- LOW $V_{CE(sat)}$
- High switching speed.
- Complementary to TFS2411
- Pb-free package

Symbol



Outline



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	-60	V
Collector-Emitter Voltage	V_{CEO}	-60	V
Emitter-Base Voltage	V_{EBO}	-5	V
Collector Current	I_C	-600	mA
Power Dissipation @ $T_A=25$	P_d	150 (Note 1)	mW
Junction Temperature	T_j	150	°C
Storage Temperature	T_{stg}	-55~+150	°C

Note 1:When mounted on a FR-5 board with area measuring 1.0×0.75×0.062 in.



Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CBO}	-60	-	-	V	I _C =-10μA
*BV _{CEO}	-60	-	-	V	I _C =-10mA
BV _{EBO}	-5	-	-	V	I _E =-10μA
I _{CBO}	-	-	-10	nA	V _{CB} =-50V
I _{CEX}	-	-	-50	nA	V _{CE} =-30V, V _{BE(OFF)} =-0.5V
*V _{CE(sat)}	-	-0.2	-0.4	V	I _C =-150mA, I _B =-15mA
*V _{CE(sat)}	-	-0.5	-1.6	V	I _C =-500mA, I _B =-50mA
*V _{BE(sat)}	-	-	-1.3	V	I _C =-150mA, I _B =-15mA
*V _{BE(sat)}	-	-	-2.6	V	I _C =-500mA, I _B =-50mA
*h _{FE}	75	-	-	-	V _{CE} =-10V, I _C =-100μA
*h _{FE}	100	-	-	-	V _{CE} =-10V, I _C =-1mA
*h _{FE}	100	-	-	-	V _{CE} =-10V, I _C =-10mA
*h _{FE}	100	-	300	-	V _{CE} =-10V, I _C =-150mA
*h _{FE}	50	-	-	-	V _{CE} =-10V, I _C =-500mA
f _T	200	-	-	MHz	V _{CE} =-20V, I _C =-50mA, f=100MHz
C _{ob}	-	-	8	pF	V _{CB} =-10V, I _E =0A, f=1MHz

*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

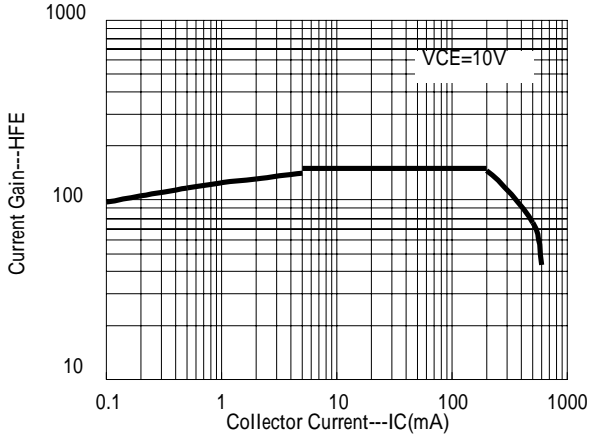
Ordering Information

Device	Package	Shipping	Marking
TFS1036	SOT-323 (Pb-free)	3000 pcs / Tape & Reel	20

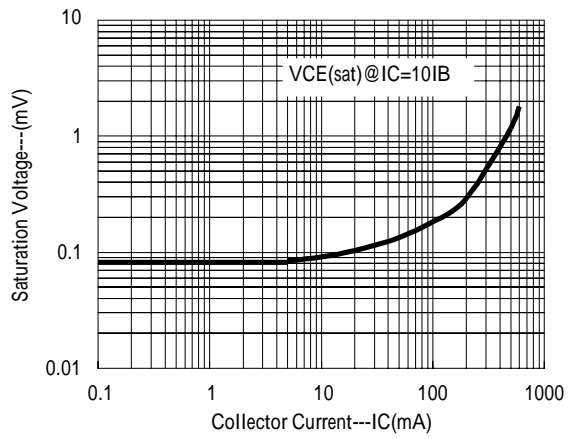


Characteristic Curves

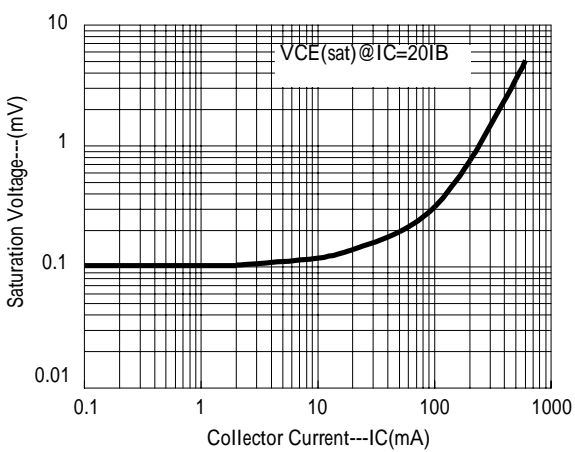
Current Gain vs Collector Current



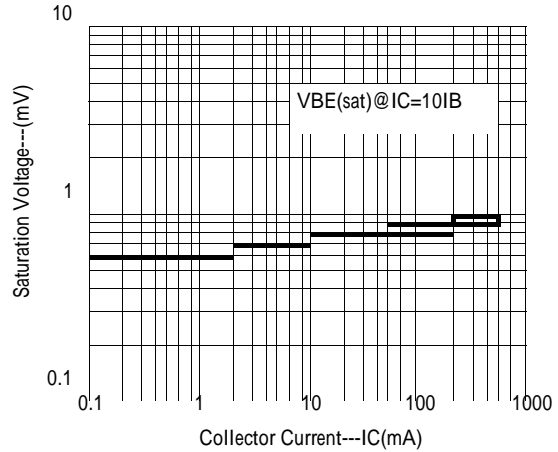
Saturation Voltage vs Collector Current



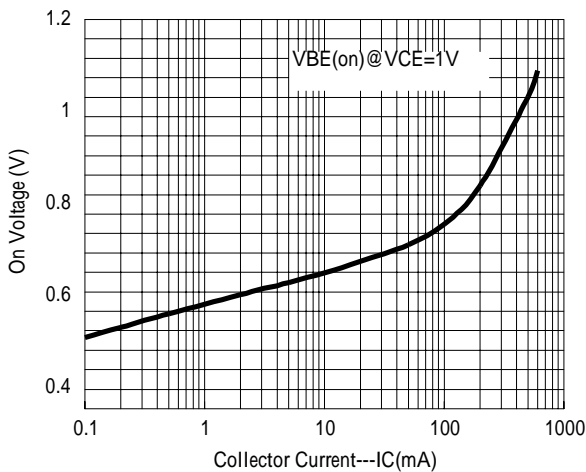
Saturation Voltage vs Collector Current



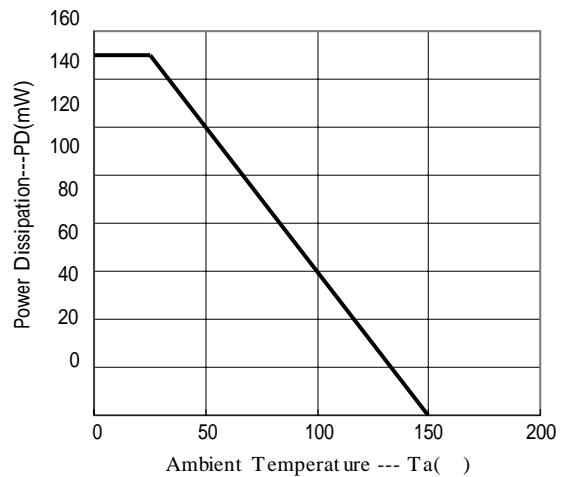
Saturation Voltage vs Collector Current



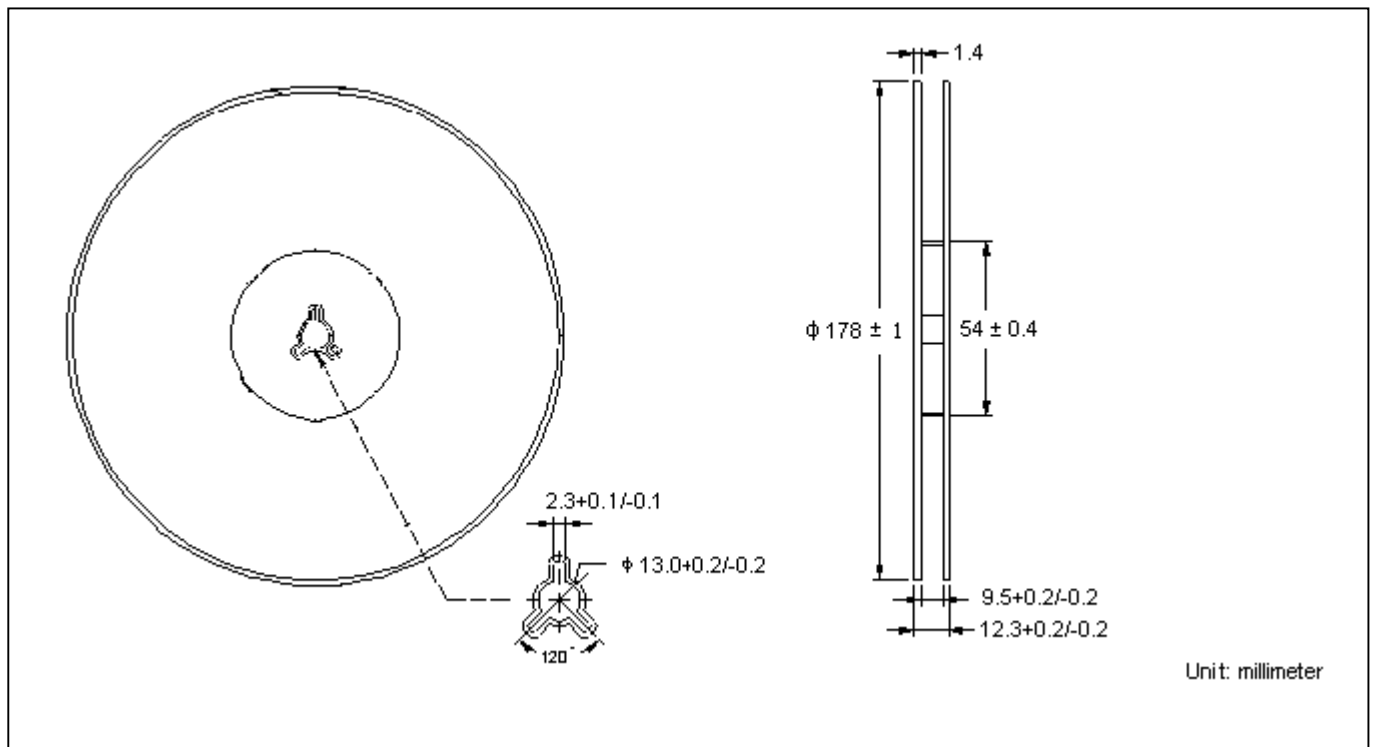
On Voltage vs Collector Current



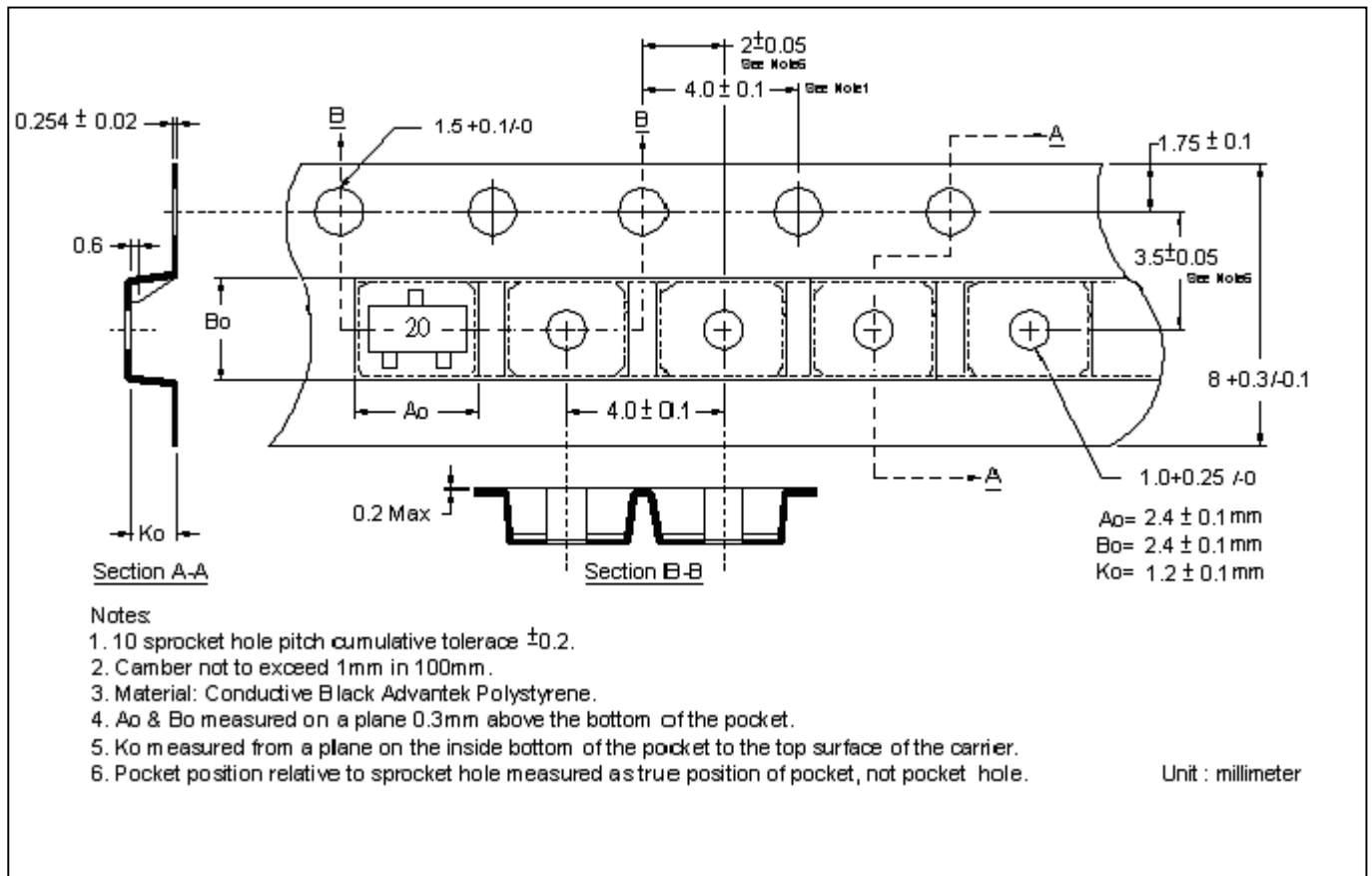
Power Derating Curve



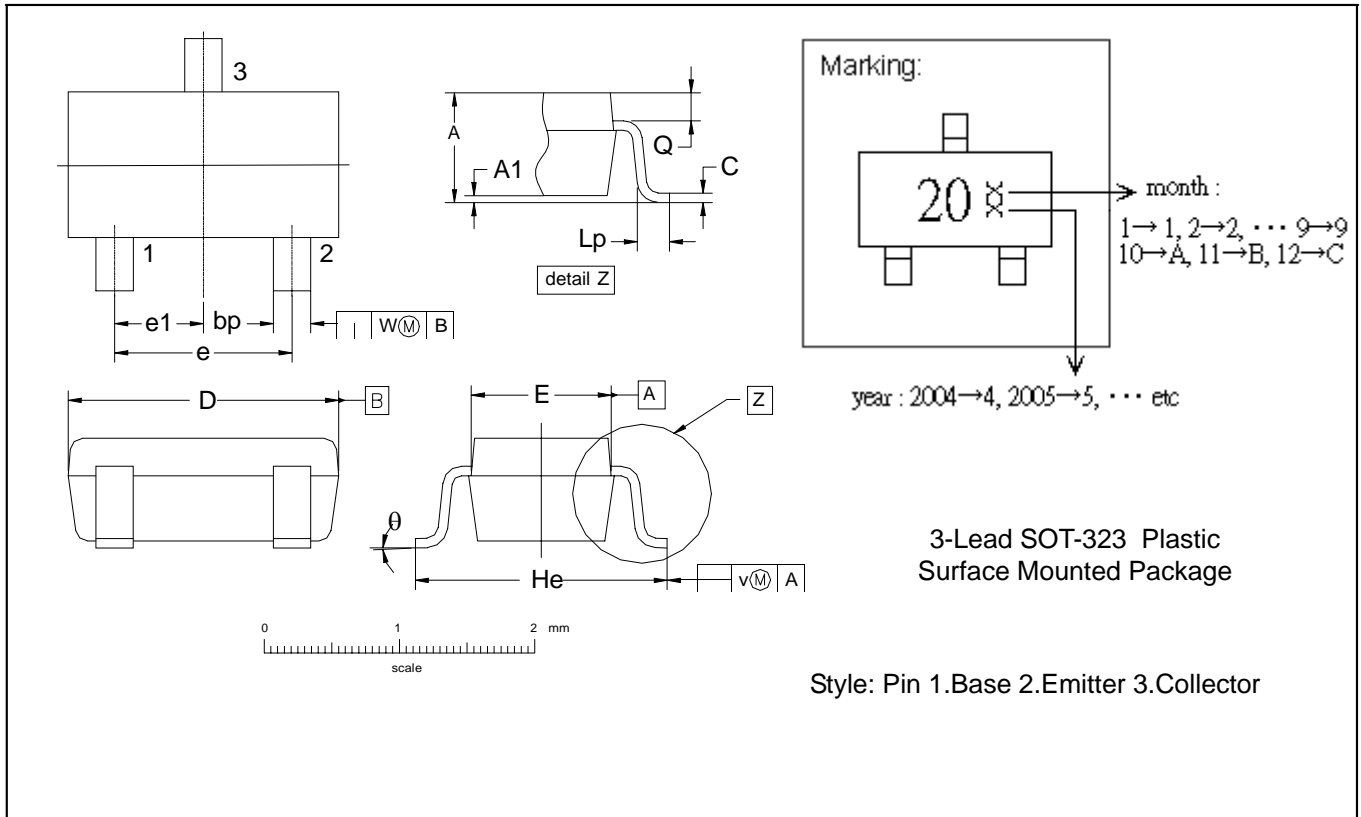
Reel Dimension



Carrier Tape Dimension



SOT-323 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0315	0.0433	0.80	1.10	e1	0.0256	-	0.65	-
A1	0.0000	0.0039	0.00	0.10	He	0.0787	0.0886	2.00	2.25
bp	0.0118	0.0157	0.30	0.40	Lp	0.0059	0.0177	0.15	0.45
C	0.0039	0.0098	0.10	0.25	Q	0.0051	0.0091	0.13	0.23
D	0.0709	0.0866	1.80	2.20	v	0.0079	-	0.2	-
E	0.0453	0.0531	1.15	1.35	w	0.0079	-	0.2	-
e	0.0512	-	1.3	-	(-	-	10°	0°

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local Tin Far sales office.

Material:

□ Lead: 42 Alloy ; solder plating

□ Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of Tin Far.
- Tin Far reserves the right to make changes to its products without notice.
- Tin Far **semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- Tin Far assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.